



## Final Product Change Notification

202203017F01 : PCA9555PW Wire Size Reduction and Conversion to Roughened Leadframe

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Nov 04, 2022 **Effective date:** Feb 02, 2023

### Management summary

PCA9555PW device will convert to a roughened leadframe for improved reliability. Additionally, the wire size will change from 25um to 20um for material standardization which will de-risk potential delays due to material imbalances.

### Change Category

- |                                                    |                                                           |                                                      |                                            |                                                               |
|----------------------------------------------------|-----------------------------------------------------------|------------------------------------------------------|--------------------------------------------|---------------------------------------------------------------|
| <input type="checkbox"/> Wafer<br>Fab<br>Process   | <input type="checkbox"/> Assembly<br>Process              | <input type="checkbox"/> Product Marking             | <input type="checkbox"/> Test<br>Process   | <input type="checkbox"/> Design                               |
| <input type="checkbox"/> Wafer<br>Fab<br>Materials | <input checked="" type="checkbox"/> Assembly<br>Materials | <input type="checkbox"/> Mechanical<br>Specification | <input type="checkbox"/> Test<br>Equipment | <input type="checkbox"/> Errata                               |
| <input type="checkbox"/> Wafer<br>Fab<br>Location  | <input type="checkbox"/> Assembly<br>Location             | <input type="checkbox"/> Packing/Shipping/Labeling   | <input type="checkbox"/> Test<br>Location  | <input type="checkbox"/> Electrical<br>spec./Test<br>coverage |
| <input type="checkbox"/> Firmware                  | <input type="checkbox"/> Other                            |                                                      |                                            |                                                               |

## PCN Overview

### Description

ATBK will convert to a roughened leadframe for quality improvement and will standardize to 20 um wire.

### Reason

The roughened leadframe offers superior delamination performance after customer SMT. Conversion to 20 um improves manufacturing efficiencies by standardizing wire size.

## Identification of Affected Products

Product identification does not change

## Product Availability

---

### Sample Information

Samples are available upon request

### Production

Planned first shipment Feb 07, 2023

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

---

No Impact on form, fit, function, reliability or quality

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Additional information

---

Self qualification: [view online](#)

## Timing and Logistics

---

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Dec 04, 2022.

## Contact and Support

---

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Dennis Dill

**Position** QA Engineer

**e-mail address** dennis.dill@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

**About NXP Semiconductors**

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

---

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006- 2022 NXP Semiconductors. All rights reserved.